
Tuesday, October 16, 15:00, Room “A”

MICROSYSTEM TECHNOLOGY

Session MT: Oral presentations

Chair:

C.V. Falub, Laboratory for Solid State Physics,
ETH-Zurich, Switzerland

A. Dinescu, IMT Bucharest, Romania

Invited Paper *EV GROUP-PUSHING MEMS ON THEIR MOVE*, **R. Staudinger**, EV Group, Austria.
15:00

MT.1 *ANNEALING EFFECTS AND OPTICAL PROPERTIES OF Si:SiO₂ FILMS PREPARED BY RADIO FREQUENCY SPUTTER*, **K. Tanaka**, **N. Happo**, **M. Fujiwara**, Hiroshima City Univ., Japan.
15:30

MT. 2 *WAFER RESISTIVITY INFLUENCE OVER DRIE PROCESSES FOR TSVs MANUFACTURING*, **D. Vasilache**, **M. Chiste**, **S. Colpo**, **F. Giacomozzi**, **B. Margesin**, FBK-irst Trento, Italy.
15:50

MT. 3 *DEPOSITION CONDITION EFFECT OVER MULTILAYERS NANOCOMPOSITE MEMBRANE GROWTH*, **A. Bragaru**, **M. Kusko**, **M. Simion**, **T. Ignat**, **M. Danila**, **F. Craciunoiu**, IMT Bucharest, Romania.
16:10

MT. 4 *THERMOCOMPRESSION BONDING FOR 3D RF MEMS DEVICES USING GOLD AND SILVER AS INTERMEDIATE LAYER*, **A. Qader Ahsan Qureshi**, **S. Colpo**, **D.A. Vasilache**, **S. Girardi**, **P. Conci**, **B. Margesin**, FBK-irst Trento, Italy.
16:30

MT. 5 *INFLUENCE OF TECHNOLOGICAL CONDITIONS ON THE PROPERTIES OF CBD CdS LAYERS*, **N. Maticiuc**, **J. Hiie**, **T. Potlog***, Tallinn Univ. of Technology, Tallinn, Estonia,
16:50 *Moldova State Univ., Chisinau, Moldova.

17:30 COFFEE BREAK in Room “C” - Poster

20:30 BANQUET, RINA Sinaia Hotel, Restaurant Hall
